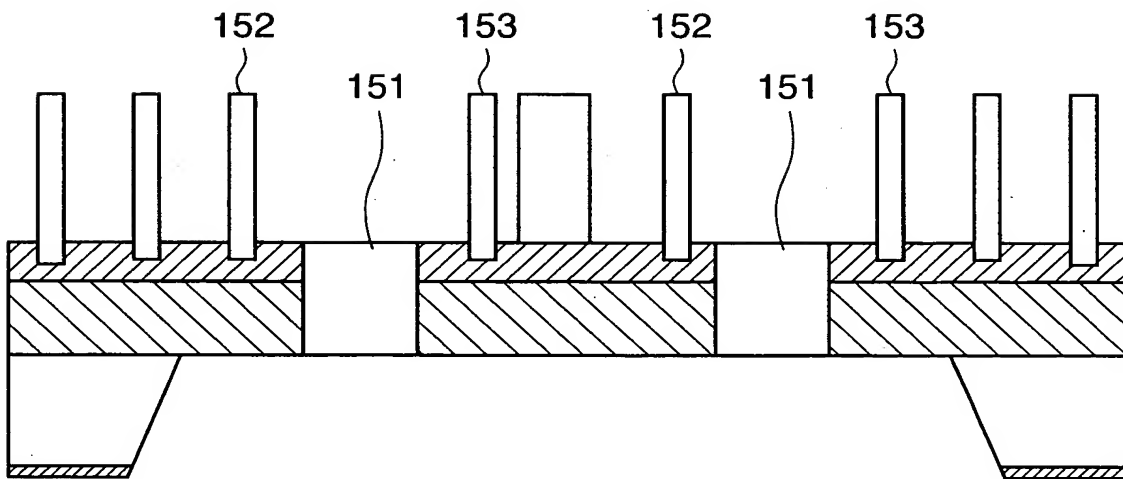
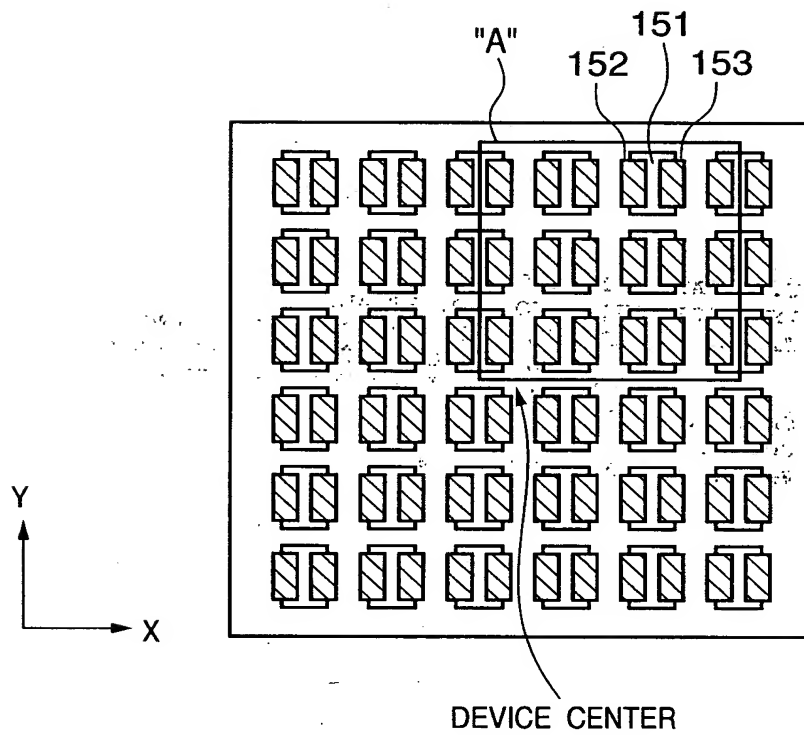
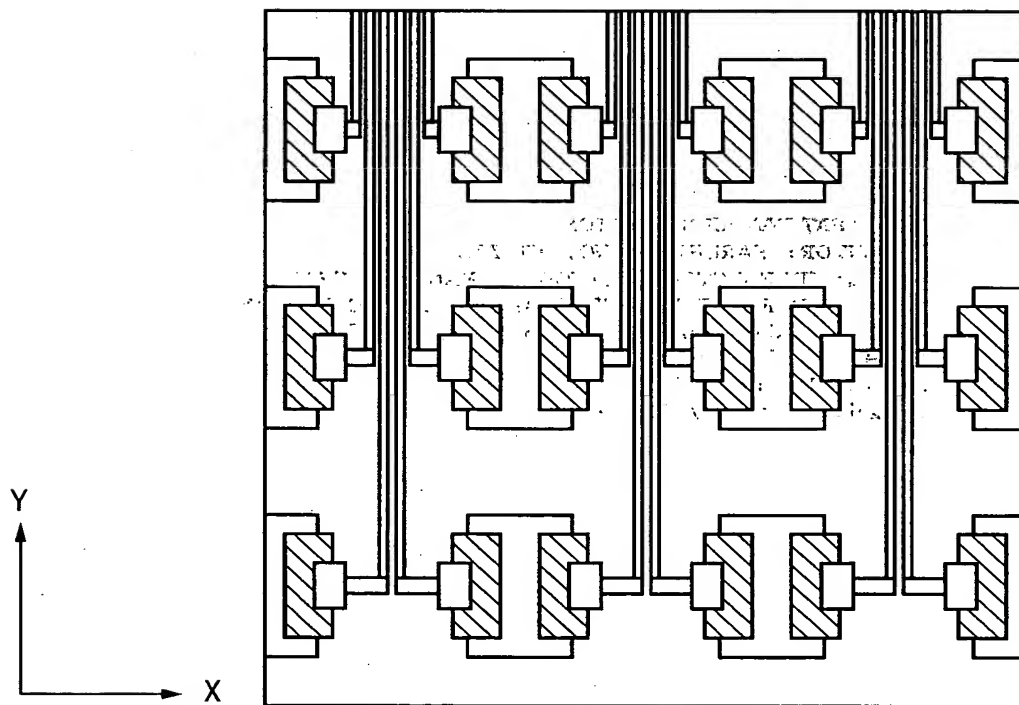


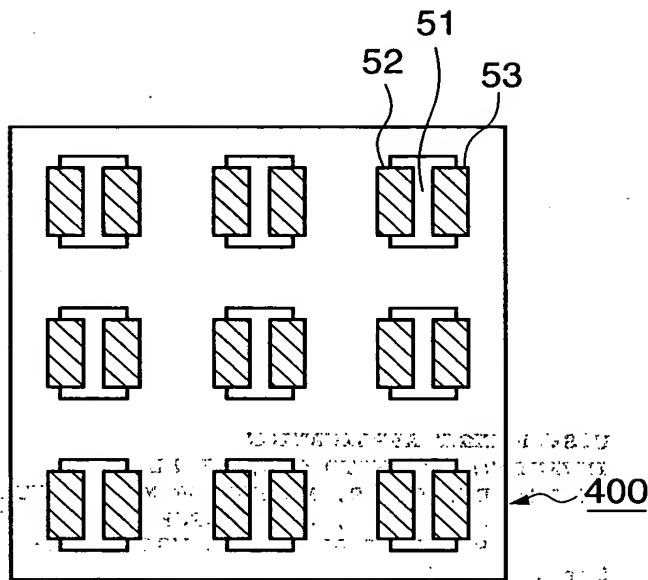
**FIG. 1**



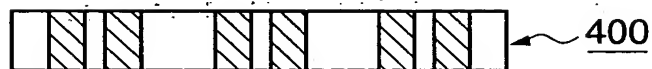
**FIG. 2**

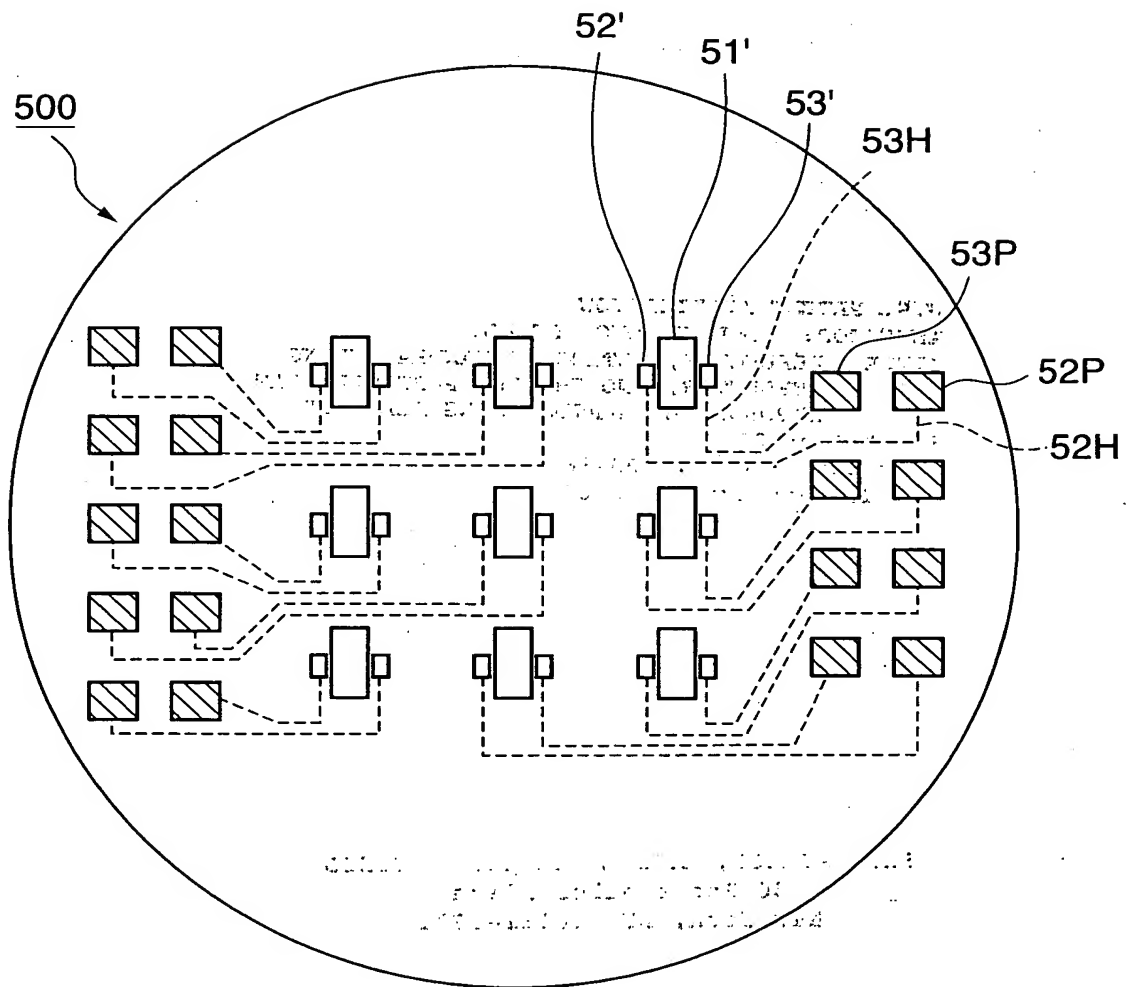
**FIG. 3**

**FIG. 4A**

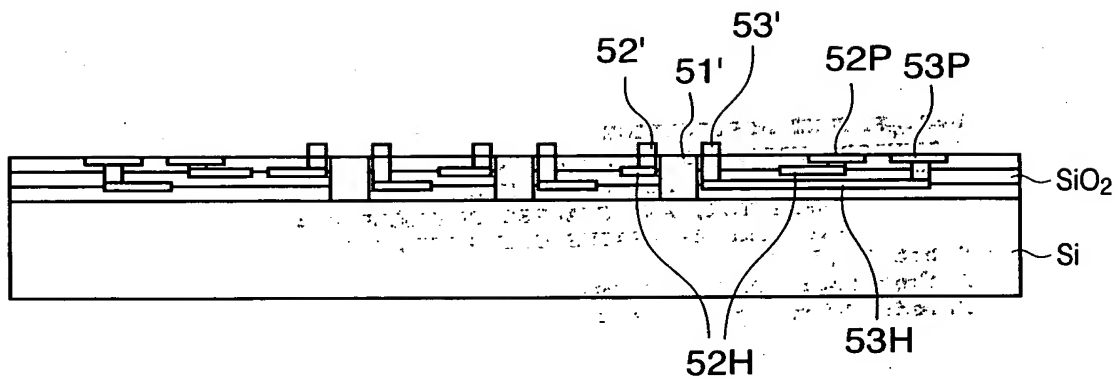


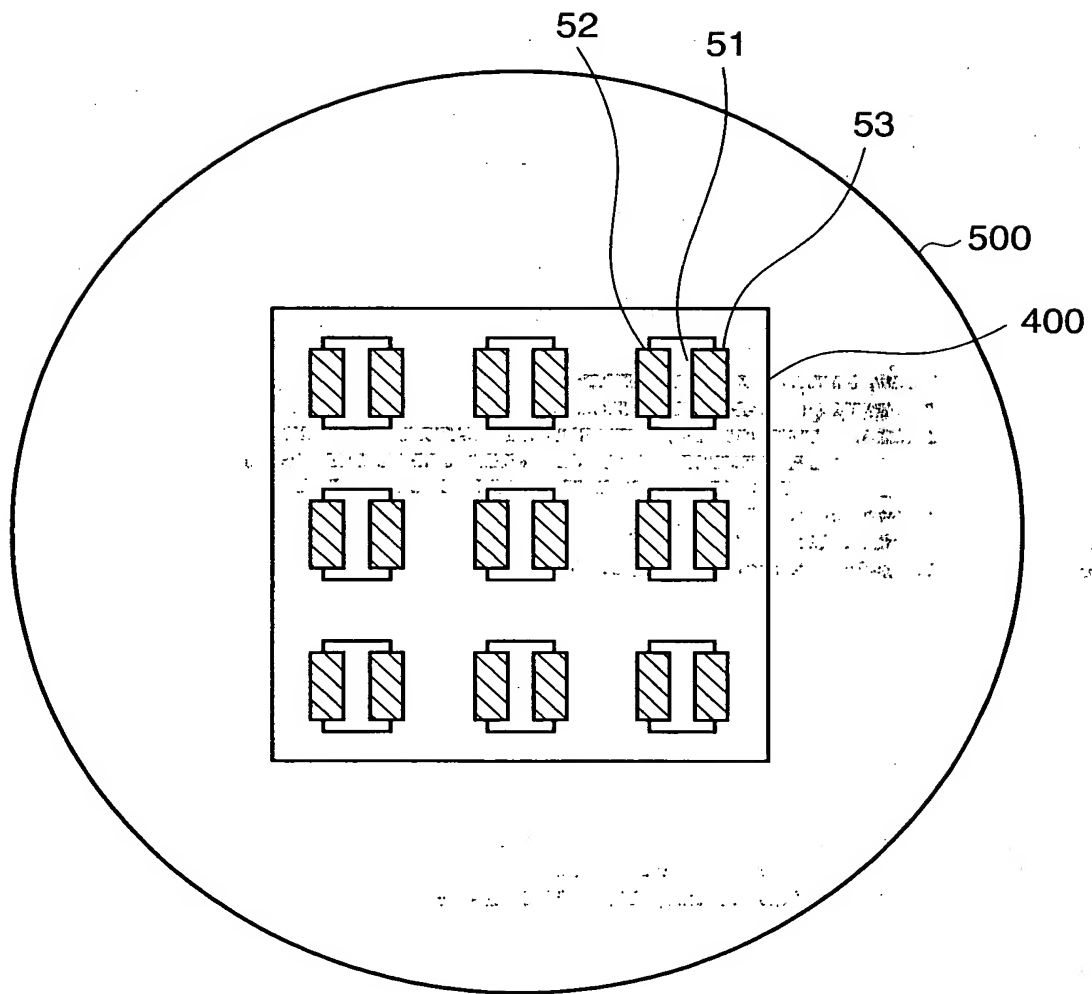
**FIG. 4B**



**FIG. 5**

**FIG. 6**



**FIG. 7**

**FIG. 8**

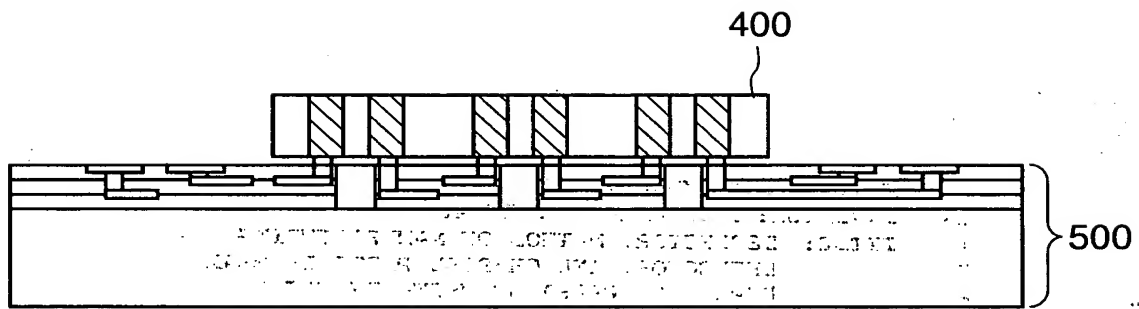
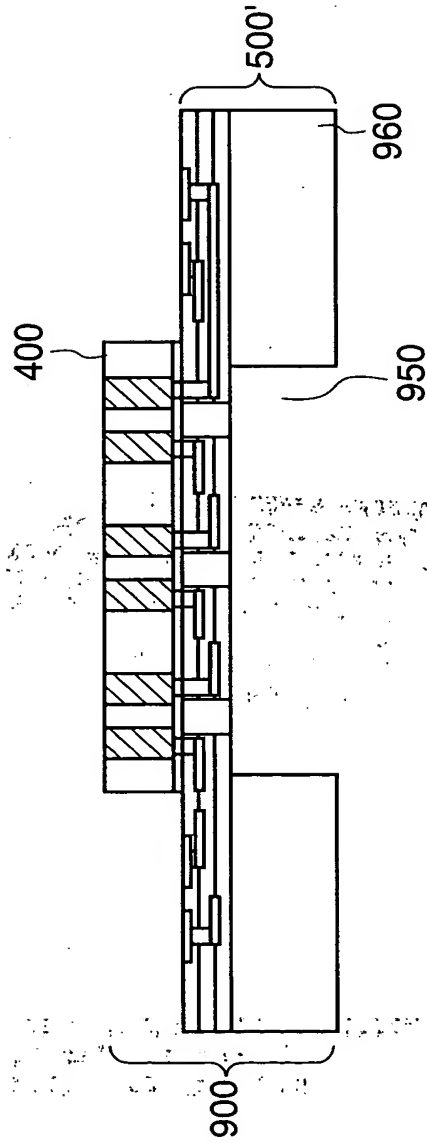


FIG. 8 is a cross-sectional view of the device assembly 100, showing the base layer 500 and the top layer 400. The top layer 400 is positioned on top of the base layer 500.

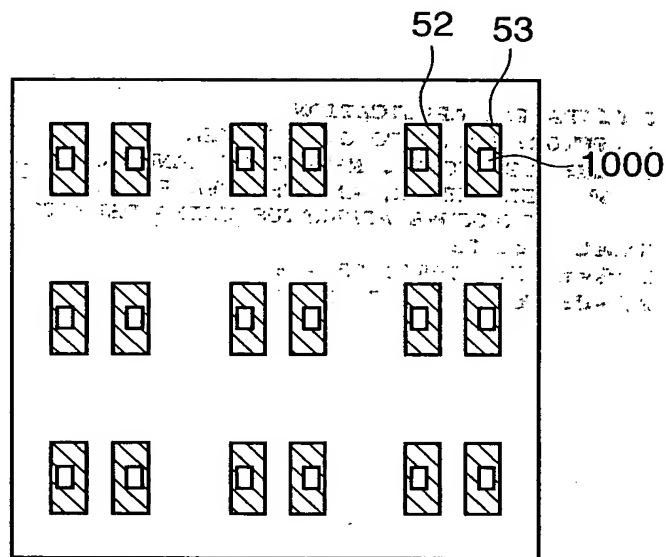


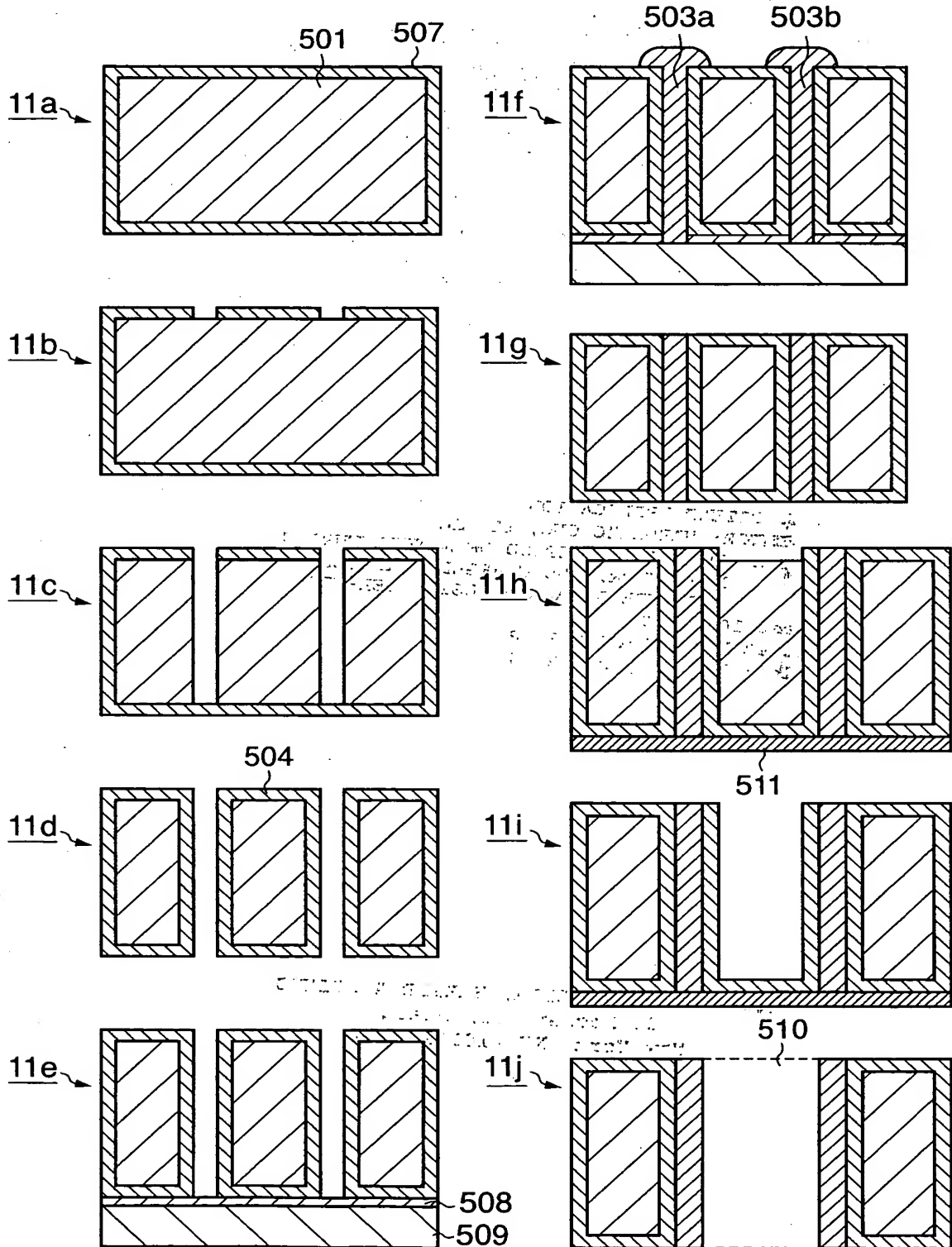
FIG. 9



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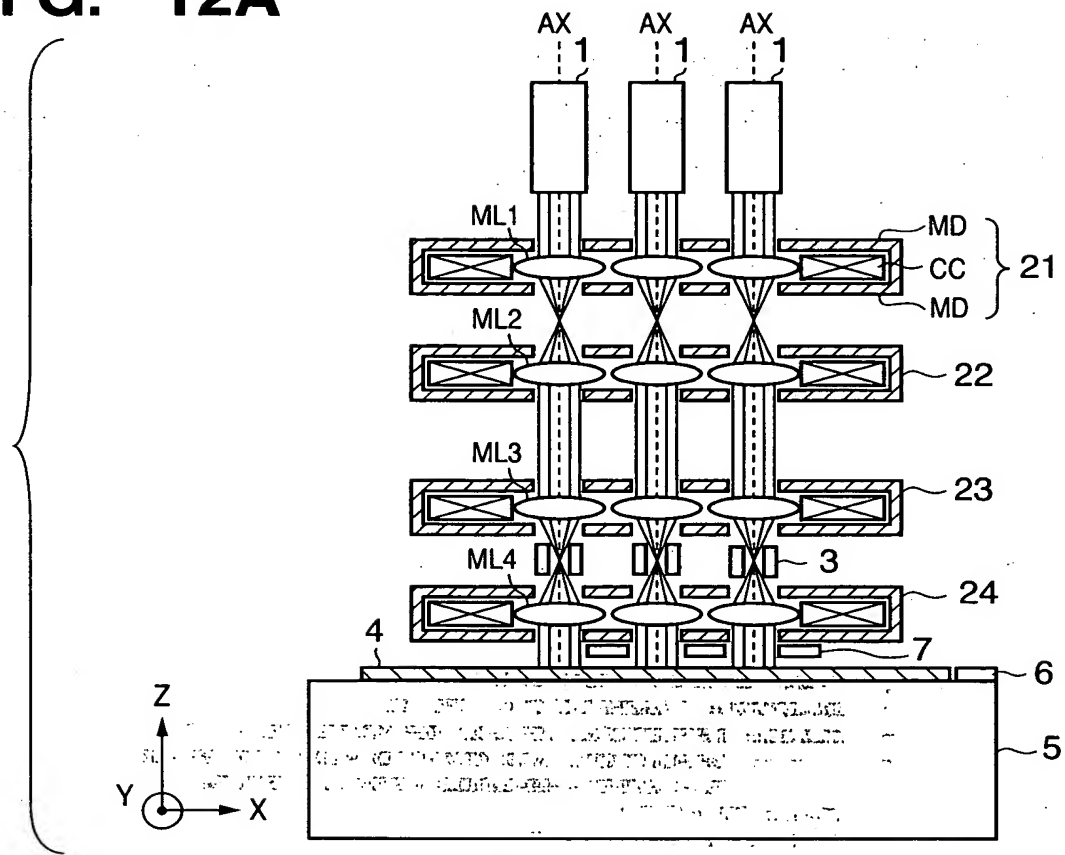
**FIG. 10**



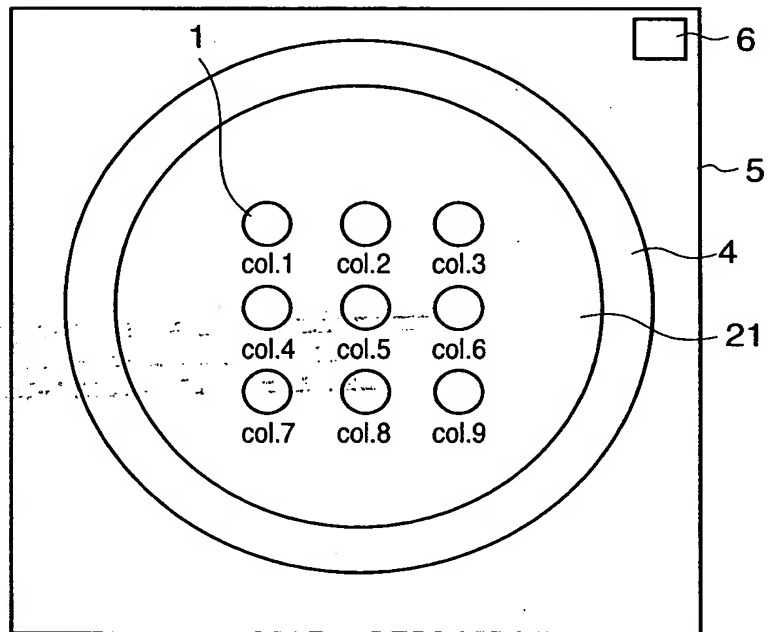
**FIG. 11**

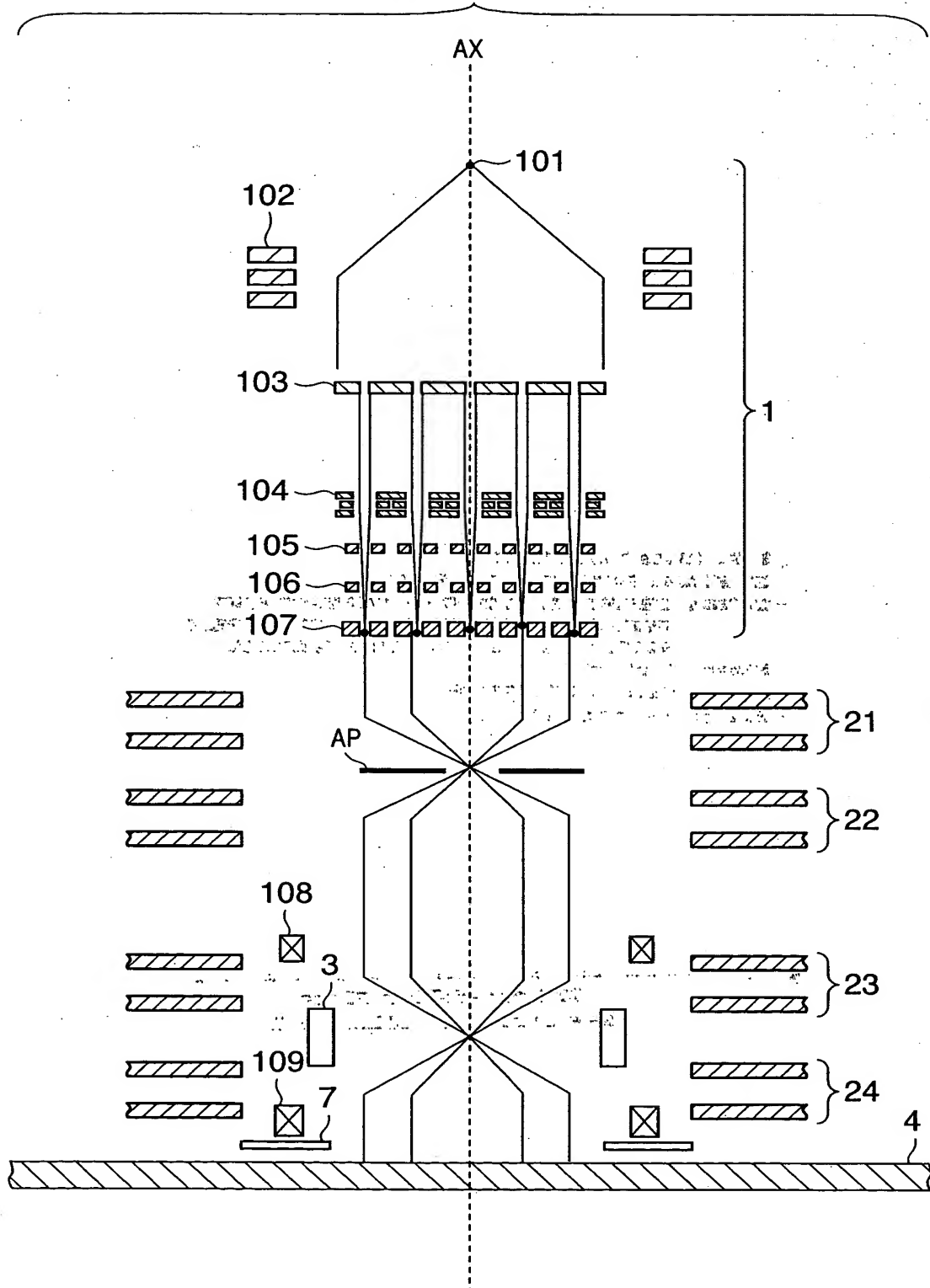
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**FIG. 12A**



**FIG. 12B**



**FIG. 13**

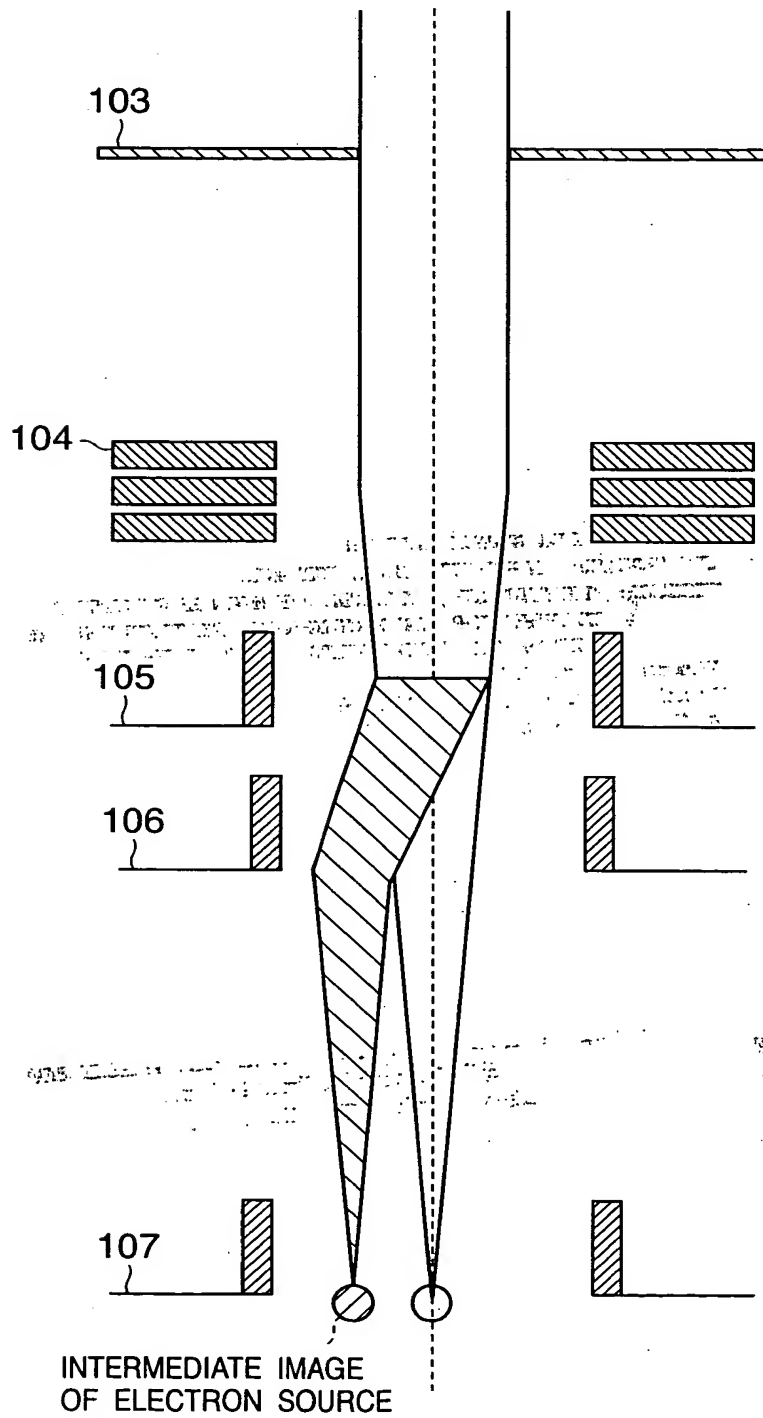
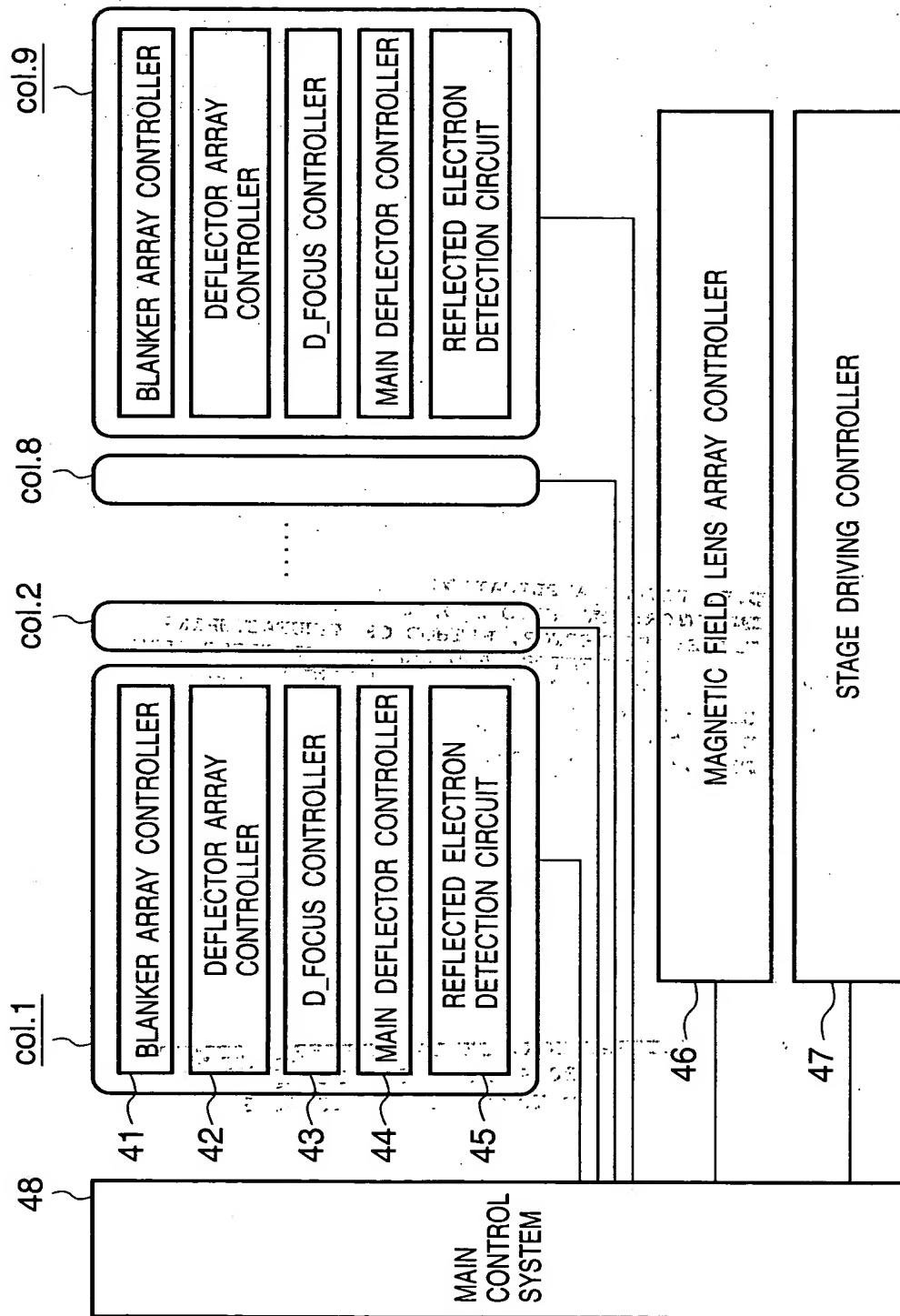
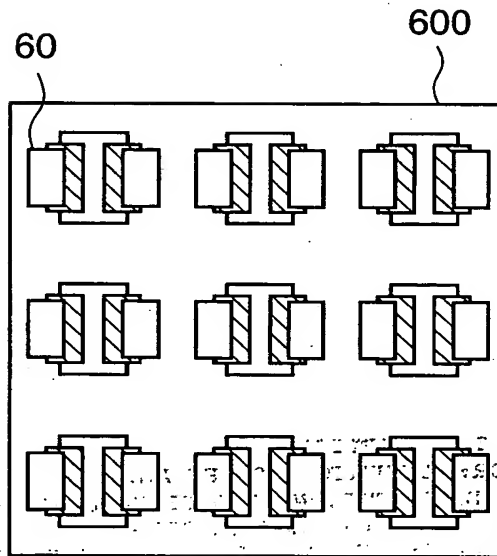
**FIG. 14**

FIG. 15



**FIG. 16A**



**FIG. 16B**





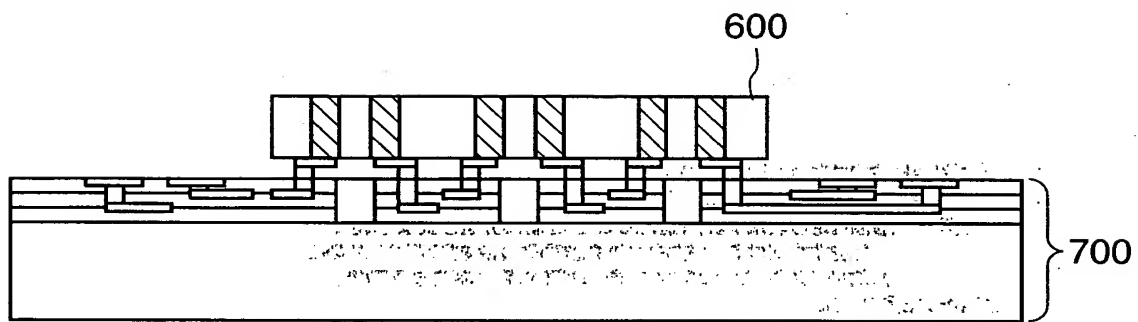
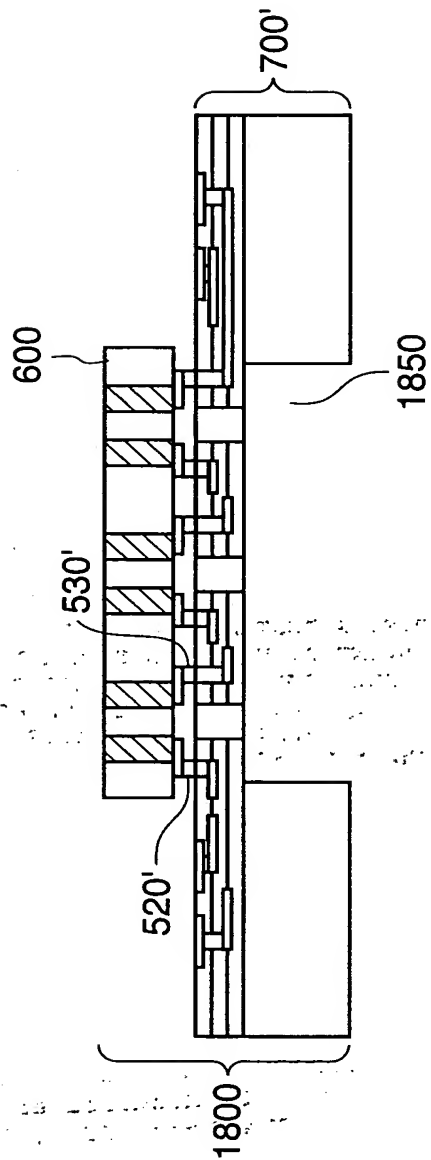
**FIG. 17**

FIG. 18



**FIG. 19**

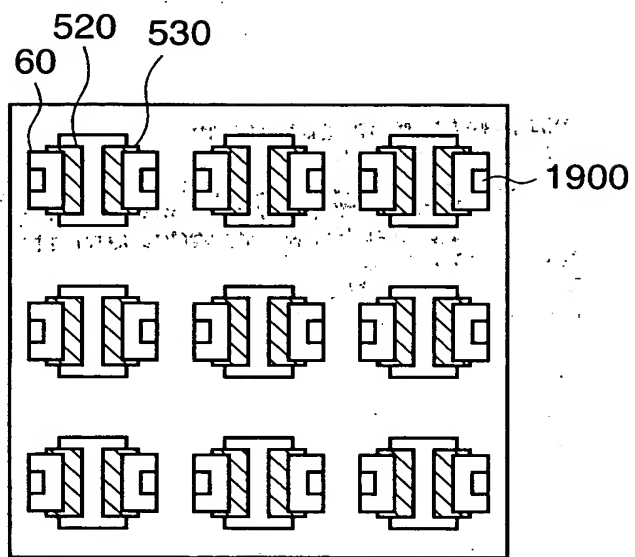
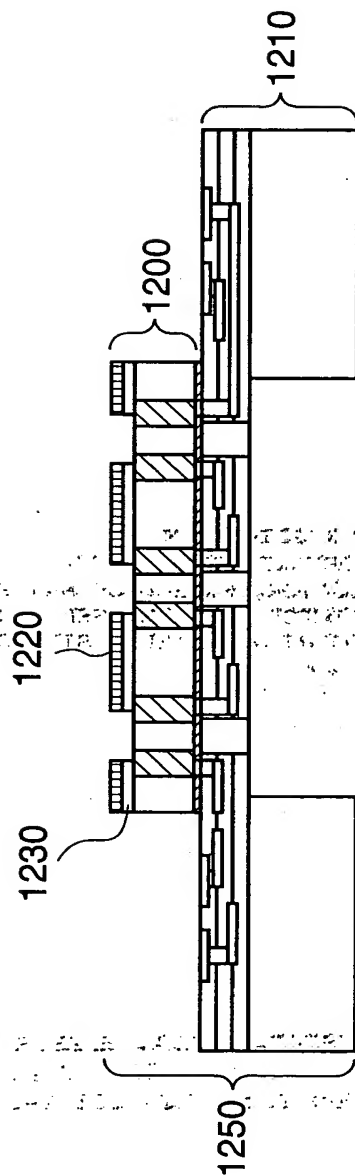
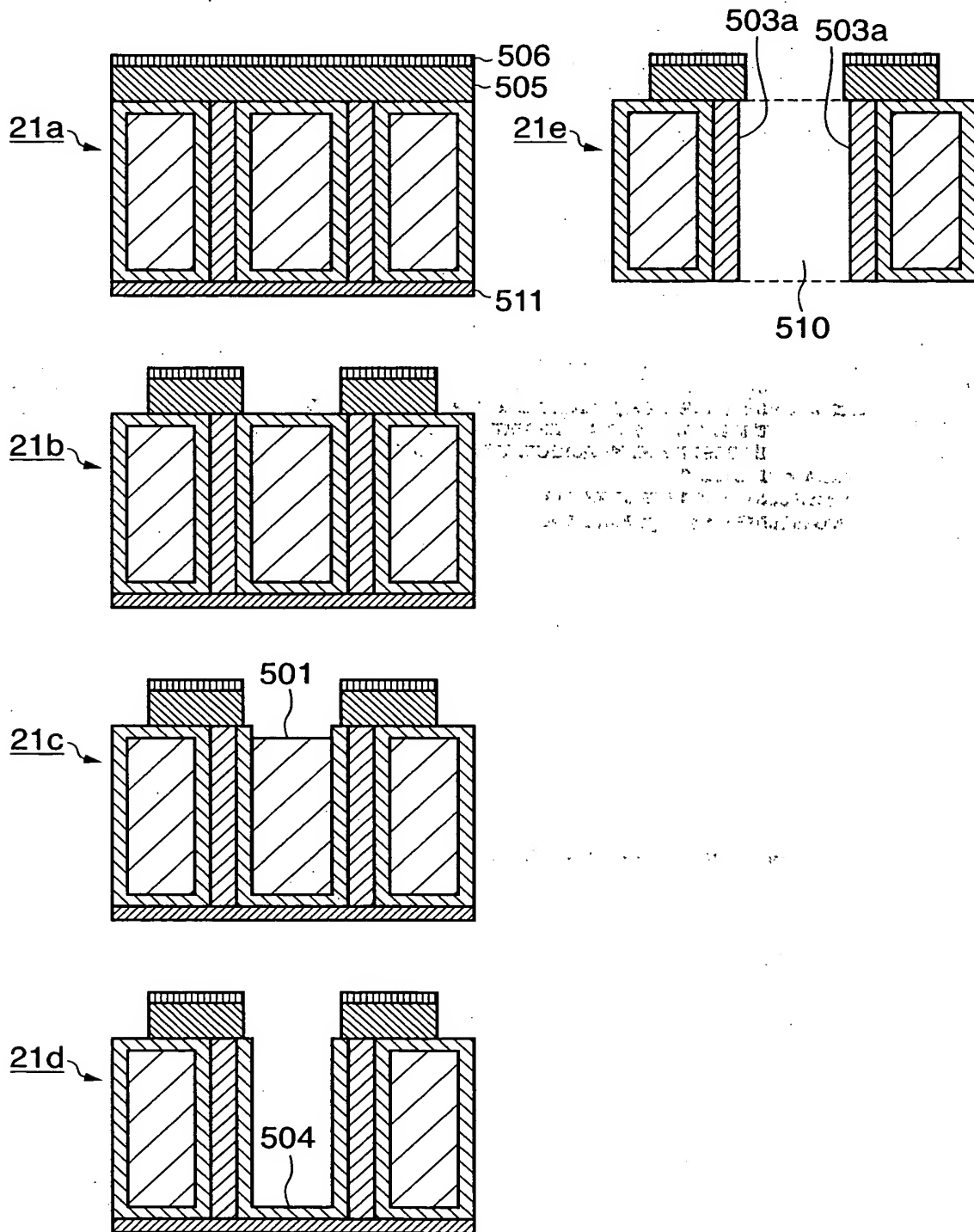
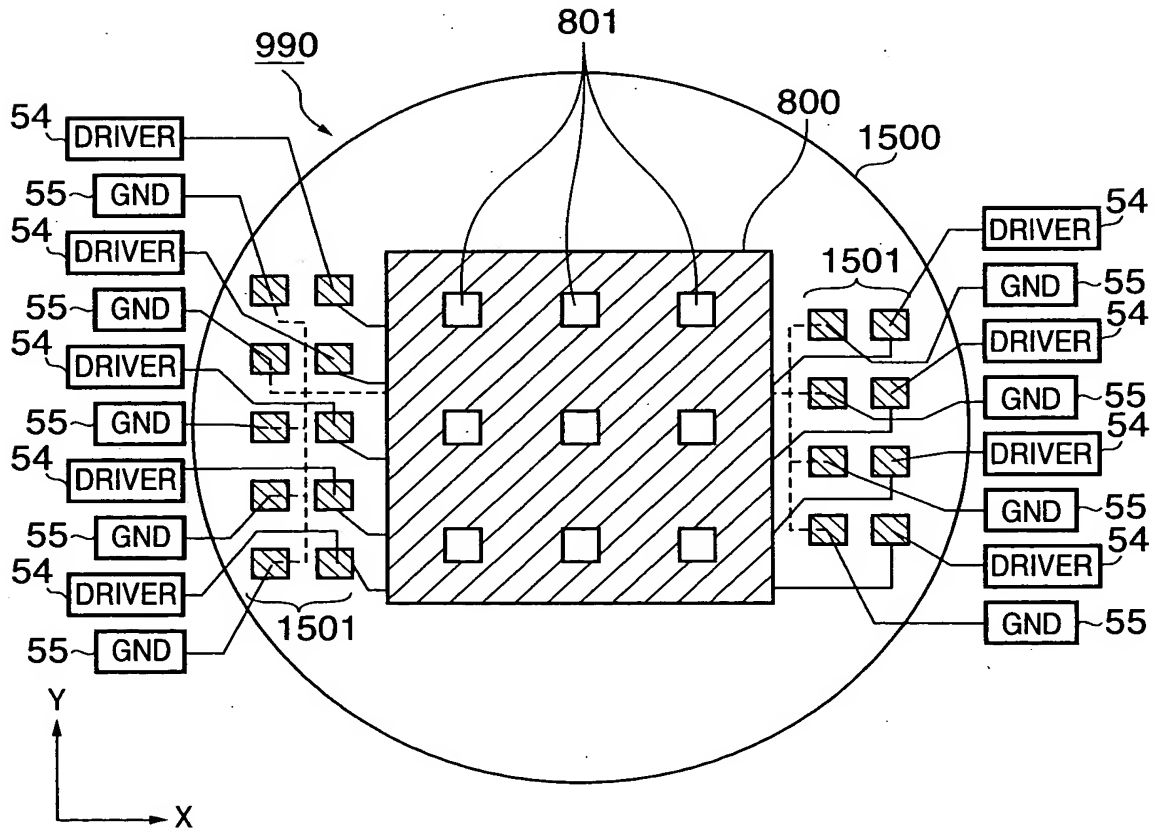
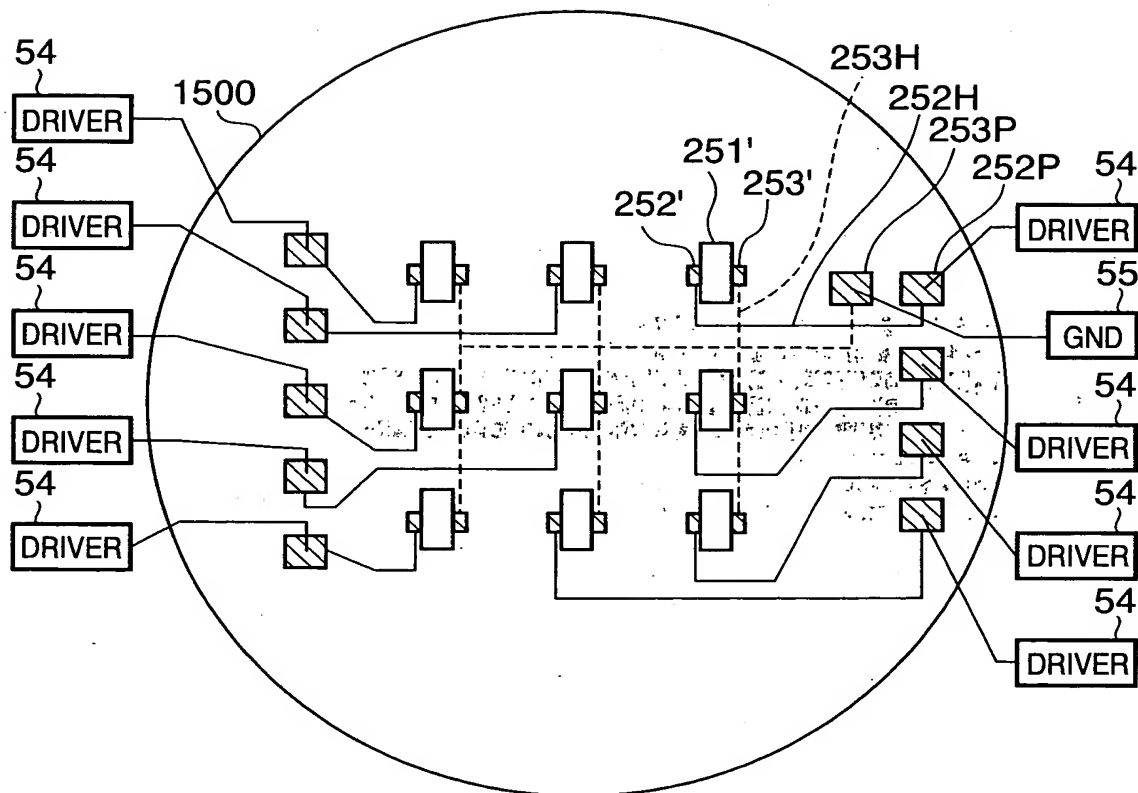


FIG. 20

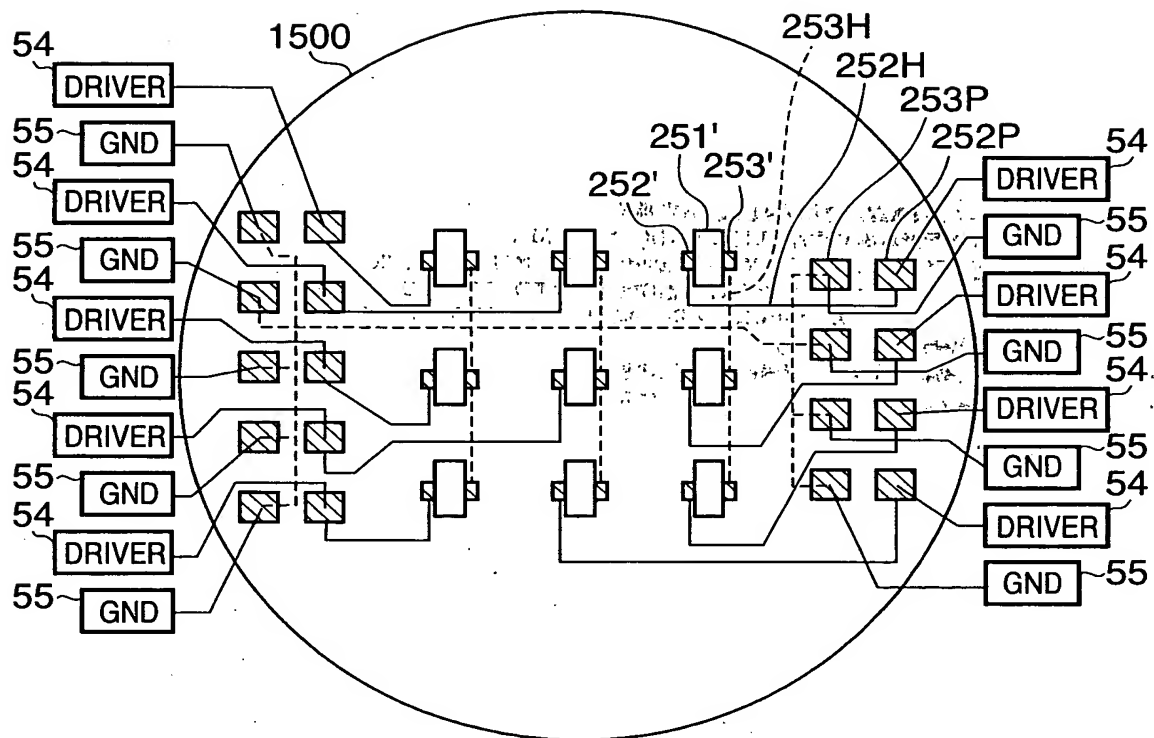


**FIG. 21**



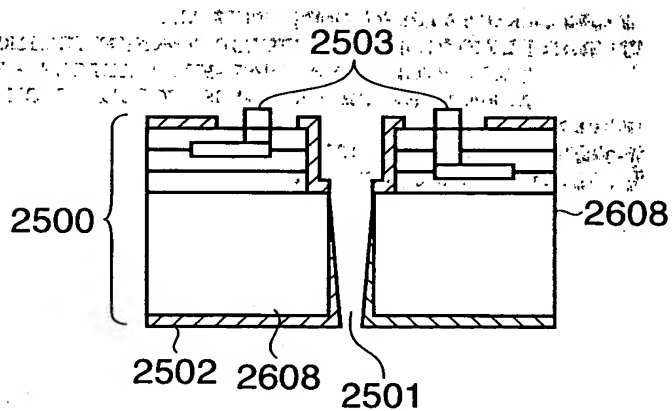
**FIG. 23**

**FIG. 24**





**FIG. 25**



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**FIG. 26**

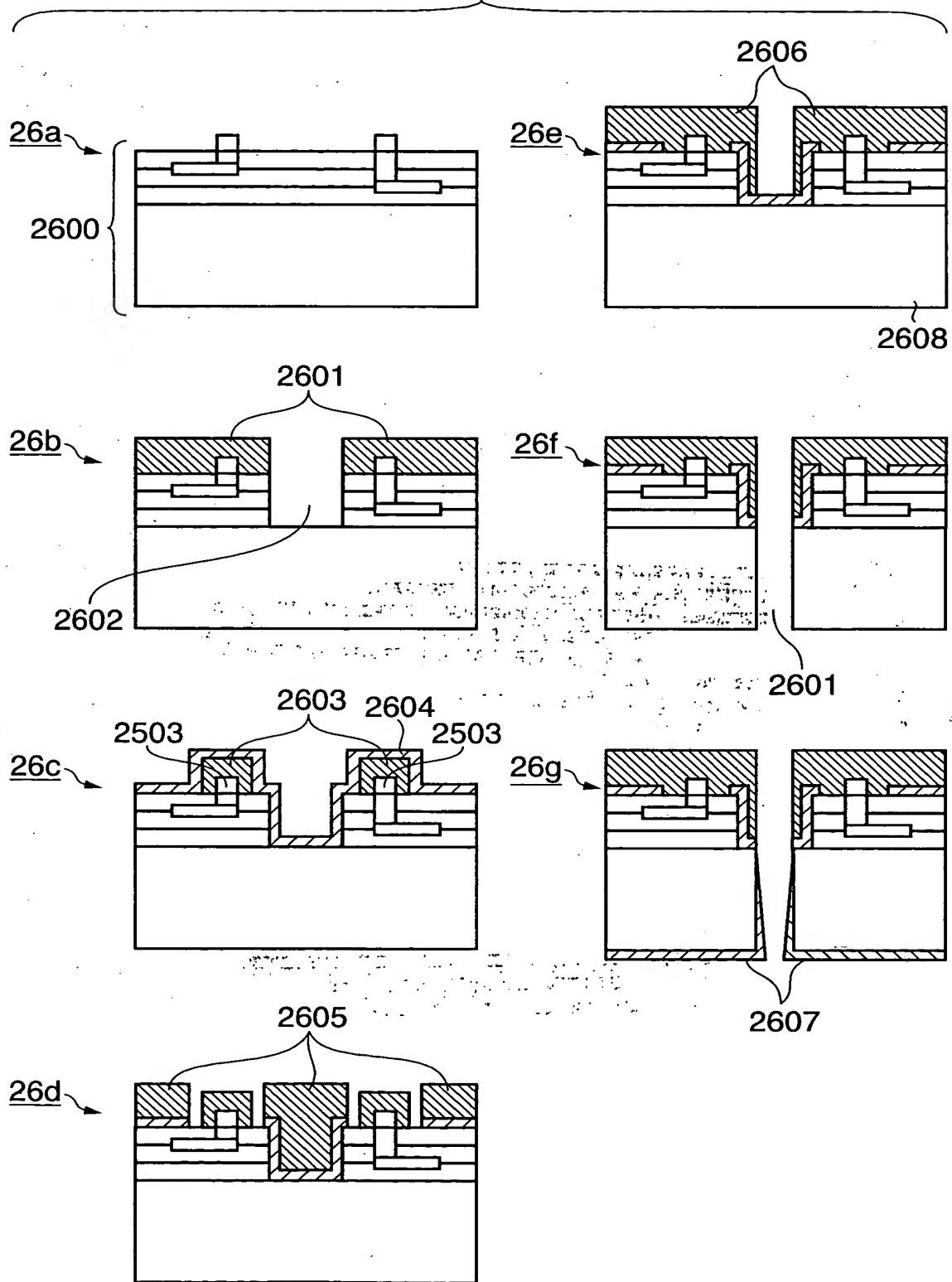
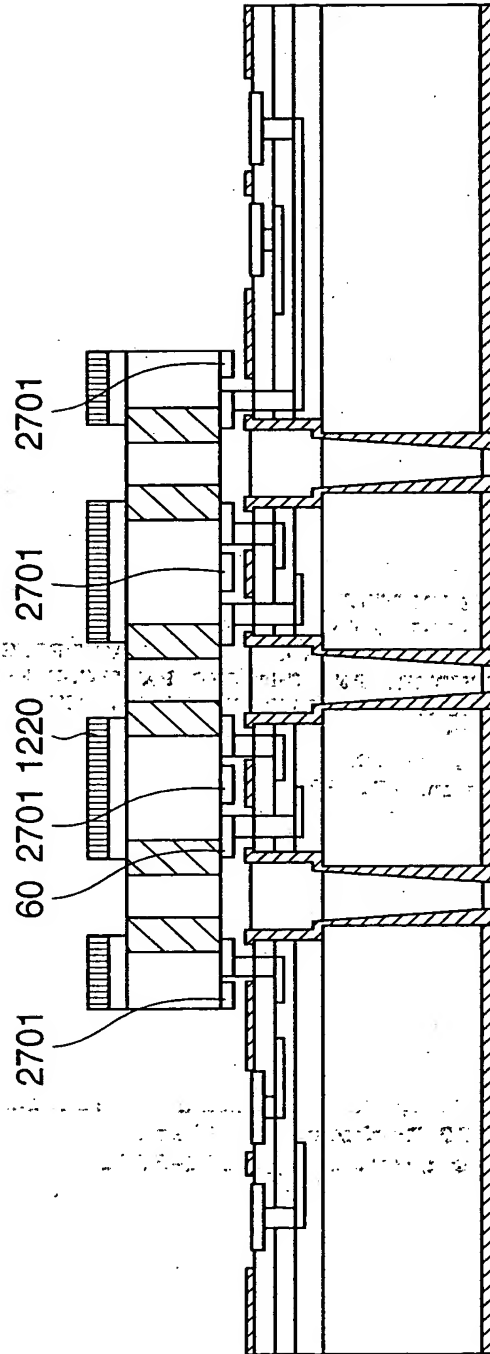


FIG. 27



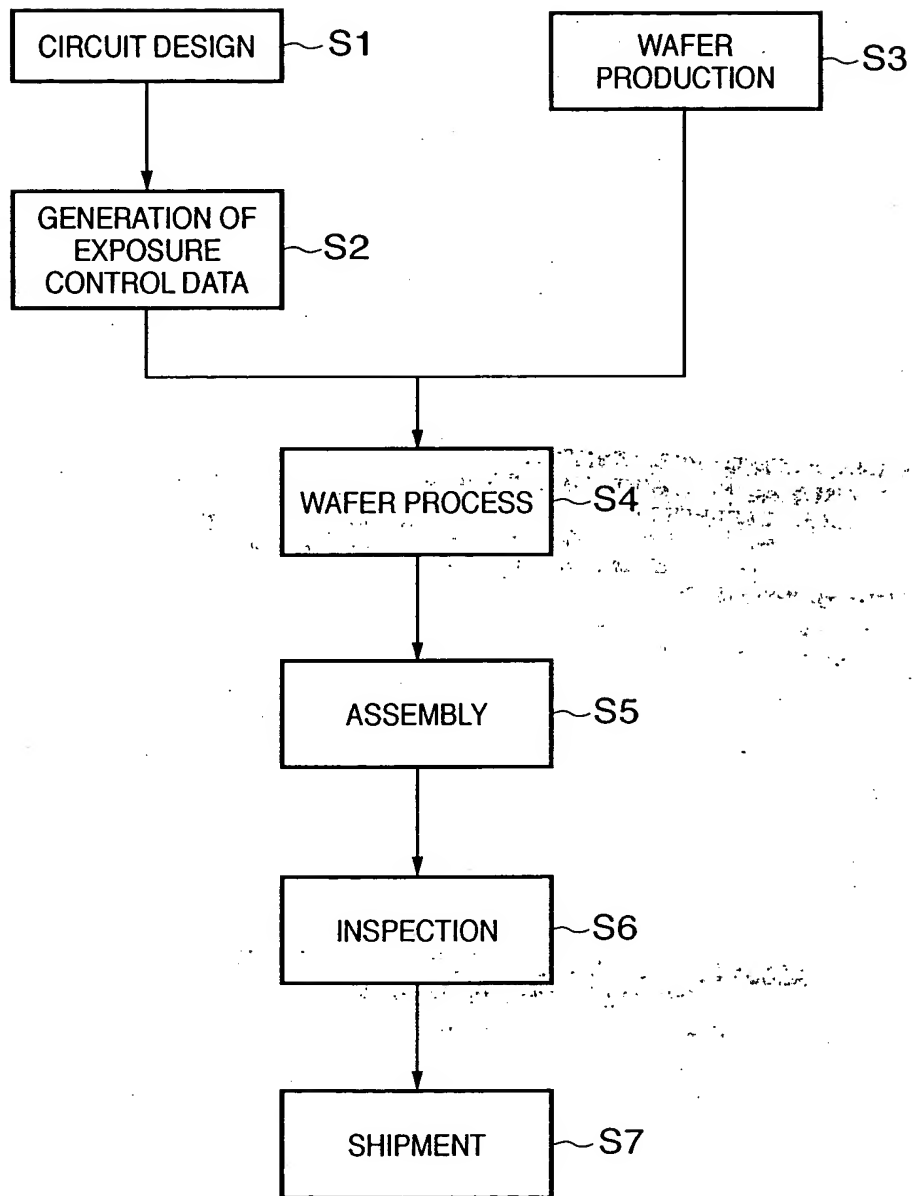
**FIG. 28**

FIG. 29

